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17 **Pro Hac application forthcoming*
18 Attorneys for Plaintiff

19 **IN THE UNITED STATES DISTRICT COURT**
20 **FOR THE SOUTHERN DISTRICT OF CALIFORNIA**

21
22 BELL SEMICONDUCTOR, LLC
23 Plaintiff,
24 v.
25 NXP USA, INC.
26 Defendant.

Case No. 3:22-cv-01527-TWR-DDL
FIRST AMENDED COMPLAINT
JURY TRIAL DEMANDED

1 Plaintiff Bell Semiconductor, LLC (“Bell Semic” or “Plaintiff”) brings this
2 Complaint against Defendant NXP USA, Inc. (“NXP”) for infringement of U.S. Patent
3 No. 7,231,626 (“the ’626 patent”). Plaintiff, on personal knowledge of its own acts, and
4 on information and belief as to all others based on investigation, alleges as follows:

5 **SUMMARY OF THE ACTION**

6 1. This is a patent infringement suit relating to NXP’s unauthorized and
7 unlicensed use of the ’626 patent. The circuit design methodologies claimed in the ’626
8 patent are used by NXP in the production of one or more of its semiconductor chips,
9 including at least the NXP LS1043A Quad-Core Networking Processor devices (“NXP
10 Accused Product”).

11 2. Traditionally, the process flow for IC design is highly linear, with each phase
12 of the design process depending on the previous steps. Accordingly, when revisions to
13 portions of the physical design are made, as typically happens numerous times during
14 the design process, all the subsequent steps typically need to be redone in their entirety
15 for at least the layer, if not the entire device. This is because regardless of the size or
16 extent of the revision to the physical design, the changes must be merged into a much
17 larger integrated circuit design and then the remaining steps of the design process flow
18 re-run.

19 3. Before the inventions claimed in the ’626 patent, the typical turnaround time
20 for implementing a change to the physical design for cutting edge devices was
21 approximately one week regardless of the size of the change. This is extremely
22 inefficient in most instances where the change relates to only a small fraction of the
23 overall design. See Ex. A at 3:16–18 & Fig. 1.

24 4. The ’626 patent’s inventors solved this problem by defining a window that
25 encloses a change specified by the revision to physical design. The window defines an
26 area that is less than the area of the entire circuit design. Only the nets within that
27 window are routed pursuant to the revision, leaving the remaining nets in the design
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1 unaffected. Then, the results of that incremental routing are inserted into a copy of the
2 original IC design to produce a revised IC design that effects the physical design change
3 without needing to redo the entire process flow.

4 5. Semiconductor devices include different kinds of materials to function as
5 intended. For example, these devices typically include both metal (*i.e.*, conductor) and
6 insulator materials, which are deposited or otherwise processed sequentially in layers
7 to form the final device. These layers—and the interconnects and components formed
8 within them—have gotten much smaller over time, increasing the performance of these
9 devices dramatically. As a result, it has become even more important to keep the layers
10 planar as the device is being built because defects and warpage can cause fabrication
11 issues and malfunctioning of the device. Manufacturers use a process called Chemical
12 Mechanical Planarization/Polishing (“CMP”) to smooth out the surface of the device to
13 prepare the device for further processing, such as deposition of another layer. This
14 allows subsequent layers to be built and connected more easily with fewer opportunities
15 for short circuits or other errors that render the device defective. CMP functions best
16 when there is a certain density and variance of the same material on the surface of the
17 chip. This is because different materials will be “polished” away at different rates,
18 leading to erosion or dishing on the surface. To reduce this problem “dummy” material,
19 also known as “dummy fill,” is typically inserted into low-density regions of the device
20 to increase the overall uniformity of the structures on the surface of the layer and reduce
21 the density variability across the surface of the device. However, dummy fill can
22 increase capacitance if it is placed too close to signal wires, which slows the
23 transmission speed of signals and degrades the overall performance of the device.

24 6. Bell Semic brings this action to put a stop to NXP’s unauthorized and
25 unlicensed use of the inventions claimed in the ’626 patent.

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1 **THE PARTIES**

2 7. Plaintiff Bell Semic is a limited liability company organized under the
3 laws of the State of Delaware with a place of business at One West Broad Street, Suite
4 901, Bethlehem, PA 18018.

5 8. Bell Semic stems from a long pedigree that began at Bell Labs. Bell Labs
6 sprung out of the Bell System as a research and development laboratory, and eventually
7 became known as one of America’s greatest technology incubators. Bell Labs
8 employees invented the transistor in 1947 in Murray Hill, New Jersey. It was widely
9 considered one of the most important technological breakthroughs of the time, earning
10 the inventors the Nobel Prize in Physics. Bell Labs made the first commercial
11 transistors at a plant in Allentown, Pennsylvania. For decades, Bell Labs licensed its
12 transistor patents to companies throughout the world, creating a technological boom
13 that led to the use of transistors in the semiconductor devices prevalent in most
14 electronic devices today.

15 9. Bell Semic, a successor to Bell Labs’ pioneering efforts, owns over 1,900
16 worldwide patents and applications, approximately 1,500 of which are active United
17 States patents. This patent portfolio of semiconductor-related inventions was
18 developed over many years by some of the world’s leading semiconductor companies,
19 including Bell Labs, Lucent Technologies, Agere Systems, and LSI Logic and LSI
20 Corporation (“LSI”). This portfolio reflects technology that underlies many important
21 innovations in the development of semiconductors and integrated circuits for high-tech
22 products, including smartphones, computers, wearables, digital signal processors, IoT
23 devices, automobiles, broadband carrier access, switches, network processors, and
24 wireless connectors.

25 10. The principals of Bell Semic all worked at Bell Labs’ Allentown facility,
26 and have continued the rich tradition of innovating, licensing, and helping the industry
27 at large since those early days at Bell Labs. For example, Bell Semic’s CTO was a LSI
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1 Fellow and Broadcom Fellow. He is known throughout the world as an innovator with
2 more than 300 patents to his name, and he has a sterling reputation for helping
3 semiconductor fabs improve their efficiency. Bell Semic's CEO took a brief hiatus from
4 the semiconductor world to work with Nortel Networks in the telecom industry during
5 its bankruptcy. His efforts saved the pensions of tens of thousands of Nortel retirees
6 and employees. In addition, several Bell Semic executives previously served as
7 engineers at many of these companies and were personally involved in creating the
8 ideas claimed throughout Bell Semic's extensive patent portfolio.

9 11. On information and belief, NXP has its principal place of business and
10 headquarters at 6501 William Cannon Drive West, Austin, TX 78735.

11 12. On information and belief, NXP develops, designs, and/or manufactures
12 products in the United States, including in this District, according to the '626 patented
13 processes/methodologies; and/or uses the '626 patented processes/methodologies in the
14 United States, including in this District, to make products; and/or distributes, markets,
15 sells, or offers to sell in the United States and/or imports products into the United States,
16 including in this District, that were manufactured or otherwise produced using the
17 patented process. Additionally, NXP introduces those products into the stream of
18 commerce knowing that they will be sold and/or used in this District and elsewhere in
19 the United States.

20 **JURISDICTION AND VENUE**

21 13. This is an action for patent infringement arising under the Patent Laws of
22 the United States, Title 35 of the United States Code. Accordingly, this Court has
23 subject matter jurisdiction under 28 U.S.C. §§ 1331 and 1338(a).

24 14. This Court has personal jurisdiction over NXP under the laws of the State
25 of California, due at least to its substantial business in California and in this District.
26 NXP has purposefully and voluntarily availed itself of the privileges of conducting
27 business in the United States, in the State of California, and in this District by
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1 continuously and systematically placing goods into the stream of commerce through an
2 established distribution channel with the expectation that they will be purchased by
3 consumers in this District. In the State of California and in this District, NXP, directly
4 or through intermediaries: (i) performs at least a portion of the infringements alleged
5 herein; (ii) develops, designs, and/or manufactures products according to the '626
6 patented process/methodology; (iii) distributes, markets, sells, or offers to sell products
7 formed according to the '626 patented process/methodology; and/or (iv) imports
8 products formed according to the '626 patented processes/methodologies.

9 15. On information and belief, venue is proper in this Court pursuant to 28
10 U.S.C. §§ 1391 and 1400 because NXP has committed, and continues to commit, acts
11 of infringement in this District and has a regular and established place of business in
12 this District. For example, NXP maintains a regular and established place of business
13 in the District at Innovation Drive, Suite 150, San Diego, CA 92128. On information
14 and belief, NXP current employs more than 75 engineers in the San Diego area. *See*
15 Search Results for Current NXP Employees, LinkedIn (available at
16 [https://www.linkedin.com/search/results/people/?currentCompany=%5B%221088%22%5D&geoUrn=%5B%22103918656%22%2C%2290010472%22%5D&keywords=e](https://www.linkedin.com/search/results/people/?currentCompany=%5B%221088%22%5D&geoUrn=%5B%22103918656%22%2C%2290010472%22%5D&keywords=engineer&origin=FACETED_SEARCH&sid=or8)
17 [ngineer&origin=FACETED_SEARCH&sid=or8](https://www.linkedin.com/search/results/people/?currentCompany=%5B%221088%22%5D&geoUrn=%5B%22103918656%22%2C%2290010472%22%5D&keywords=engineer&origin=FACETED_SEARCH&sid=or8)) (last visited November 22, 2022).
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19 16. Currently, on information and belief, NXP is advertising more than 20 jobs
20 in the San Diego area. These positions include those that relate to the '626 patented
21 technologies, such as positions for a Principal Physical Design Engineer, SoC
22 Hardware Architect, and Senior Physical Design Engineer. *See NXP Job Listings*, NXP
23 ([https://nxp.wd3.myworkdayjobs.com/careers?Location_Country=bc33aa3152ec42d4](https://nxp.wd3.myworkdayjobs.com/careers?Location_Country=bc33aa3152ec42d4995f4791a106ed09&locations=98d67abaaa8a100fa6344859d7d49369)
24 [995f4791a106ed09&locations=98d67abaaa8a100fa6344859d7d49369](https://nxp.wd3.myworkdayjobs.com/careers?Location_Country=bc33aa3152ec42d4995f4791a106ed09&locations=98d67abaaa8a100fa6344859d7d49369)) (last visited
25 November 22, 2022).

26 17. Venue is also convenient in this District. This is at least true because of
27 this District's close ties to this case—including the technology, relevant witnesses, and
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1 sources of proof noted above—and its ability to quickly and efficiently move this case
2 to resolution.

3 18. On information and belief, Bell Semic’s cause of action arises directly
4 from NXP’s circuit design work and other activities in this District. Moreover, on
5 information and belief, NXP has derived substantial revenues from its infringing acts
6 occurring within the State of California and within this District.

7 **U.S. PATENT NO. 7,231,626**

8 19. Bell Semiconductor owns by assignment the entire right, title, and interest
9 in the ’626 patent, entitled “Method Of Implementing An Engineering Change Order
10 In An Integrated Circuit Design By Windows.”

11 20. A true and correct copy of the ’626 patent is attached as Exhibit A.

12 21. The ’626 patent issued to inventors Jason K. Hoff, Viswanathan
13 Lakshmanan, Michael Josephides, Daniel W. Prevedel, Richard D. Blinne, and
14 Johathan P. Kuppinger.

15 22. The application that resulted in issuance of the ’626 patent, United States
16 Patent Application No. 11/015,123, was filed December 17, 2004. It issued on June 12,
17 2007 and expires on July 26, 2025.

18 23. The ’626 patent generally relates to “methods of implementing an
19 engineering change order (ECO) in an integrated circuit design.” Ex. A at 1:1–13.

20 24. The background section of the ’626 patent identifies the shortcomings of
21 the prior art. More specifically, the specification describes that the prior circuit design
22 methodology was disadvantageous because “[i]n previous methods for implementing
23 an engineering change order (ECO) request in an integrated circuit design, design tools
24 are run for the entire integrated circuit design, even though the engineering change
25 order typically is only a small fraction of the size of the integrated circuit design” Ex.
26 A at 2:15–19.

1 25. The '626 patent elaborates that because “cell placement, routing, design
2 rule check validation, and timing closure run times typically scale with the size of the
3 entire integrated circuit design,” Ex. A at 2:20–22, this produced a “typical turnaround
4 time” of “about one week regardless of the size of the engineering change order. . . .
5 because although the engineering change order may only have a size of a few cells, it
6 must be merged with an integrated circuit design that typically has a much greater size.”
7 *Id.* at 2:37–44. Certain of these steps “may be especially time consuming and resource
8 intensive.” *Id.* at 3:16–17.

9 26. The inventions disclosed in the '626 patent provide many advantages over
10 the prior art. In particular, they provide a simple and efficient method for ensuring that
11 revisions to the physical design of the IC do not unduly delay the completion of the
12 design process. As the '626 patent explains, “significant savings in the resources
13 required to perform routing, design rule check verification, net delay calculation, and
14 parasitic extraction may be realized by creating windows in the integrated circuit design
15 that include only the incremental changes to the overall integrated circuit design.” Ex.
16 A at 3:19–23.

17 27. As mentioned above, this is very beneficial because it substantially
18 reduces the run time of the routing tools and related follow-on steps of the layout
19 portion of the design process flow (such as calculation of net delay, design rule check,
20 and parasitic extraction). Thus, it shortens the overall design timeline, and avoids cost
21 overruns and delays, making it less costly to make changes later in the design process
22 or more often. *See id.*

23 28. Given the aforementioned increased complexity of circuit designs and the
24 corresponding delays from design changes, these efficiency gains have become more
25 and more important in completing the design process without affecting time-to-market.
26 These significant advantages are achieved through the use of the patented inventions
27 and thus the '626 patent presents significant commercial value for chip designers.

1 29. In light of the drawbacks of the prior art, the '626 patent's inventors
2 recognized the need for a circuit design methodology in which the time required to
3 implement an ECO "depend[s] on the number of net changes in the [ECO] rather than
4 on the total number of nets in the entire integrated circuit design." Ex. A at 2:51–53.
5 The inventions claimed in the '626 patent address this need.

6 30. The '626 patent contains two independent claims and 8 total claims,
7 covering a method and computer readable medium for implementing a change order in
8 an integrated circuit design. Claim 1 reads:

9 1. A method comprising steps of:

10 (a) receiving as input an integrated circuit design;

11 (b) receiving as input an engineering change order to the integrated
12 circuit design;

13 (c) creating at least one window in the integrated circuit design that
14 encloses a change to the integrated circuit design introduced by the
15 engineering change order wherein the window is bounded by
16 coordinates that define an area that is less than an entire area of the
integrated circuit design;

17 (d) performing an incremental routing of the integrated circuit
18 design only for each net in the integrated circuit design that is
19 enclosed by the window;

20 (e) replacing an area in a copy of the integrated circuit design that
21 is bounded by the coordinates of the window with results of the
22 incremental routing to generate a revised integrated circuit design;
and

23 (f) generating as output the revised integrated circuit design.

24 31. This claim, as a whole, provides significant benefits and improvements to
25 the function of the semiconductor device design process, *e.g.*, providing a novel and
26 substantially more efficient process flow in which only the affected nets would be
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1 considered in the incremental routing. This results in substantial reduction in the
2 expected time of the design portion of producing semiconductor devices.

3 32. The claims of the '626 patent also recite inventive concepts that improve
4 the functioning of the fabrication process, particularly as to post-ECO routing. The
5 claims of the '626 patent disclose a new and novel solution to specific problems related
6 to improving semiconductor fabrication. As explained in detail above and in the '626
7 patent specification, the claimed inventions improve upon the prior art processes by
8 ignoring nets that are unaffected by an ECO in performing routing following the ECO.
9 This has the advantage of substantially reducing the impact on design schedule of ECOs
10 and other layout changes, thus increasing the efficiency of the design process and
11 making it easier to improve the design and fix design errors without unduly delaying
12 time-to-market. By making it easier to fix errors as they are found, and causing
13 substantially less incremental delay upon finding and fixing errors, the claimed
14 inventive processes also increase the performance and reliability of the finished
15 product. Because of the claimed inventive processes, individual less impactful design
16 issues that still impact design performance (albeit not on a critical scale) can be caught
17 and fixed without costing the same delay as more substantial errors.

18 **COUNT I – INFRINGEMENT OF U.S. PATENT NO. 7,231,626**

19 33. Bell Semic re-alleges and incorporates by reference the allegations of the
20 foregoing paragraphs as if fully set forth herein.

21 34. The '626 patent is valid and enforceable under the United States Patent
22 Laws.

23 35. Bell Semic owns, by assignment, all right, title, and interest in and to the
24 '626 patent, including the right to collect for past damages.

25 36. A copy of the '626 patent is attached at Exhibit A.

26 37. On information and belief, NXP has and continues to directly infringe
27 pursuant to 35 U.S.C. § 271(a) one or more claims of the '626 patent by using the
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1 patented methodology to design one or more semiconductor devices, including as one
2 example the NXP Accused Product, in the United States.

3 38. On information and belief, NXP employs a variety of design tools, for
4 example, Cadence, Synopsys, and/or Siemens tools, to perform incremental routing in
5 implementing an ECO (the “Accused Processes”) as recited in the ’626 patent claims.
6 As one example, NXP’s Accused Processes perform a method for only routing the nets
7 affected by the ECO and merging that changed area into the overall circuit layout as
8 required by claim 1 of the ’626 patent. NXP does so by employing a design tool, such
9 as at least one of a Cadence, Synopsys, and/or Siemens tool, to perform incremental
10 routing as part of implementing an ECO for the NXP Accused Product to generate a
11 revised integrated circuit design.

12 39. NXP’s Accused Processes also calculate and perform a parasitic extraction
13 only for each net in the IC design enclosed by the window defining the ECO. (This
14 parasitic extraction is also how the Accused Processes further calculate a net delay only
15 for each net in the IC design enclosed by the window defining the ECO.) NXP does so
16 by employing a design tool, such as at least one of the Cadence, Synopsys, and/or
17 Siemens tools, to perform the incremental routing during implementation of the ECO
18 for the NXP Accused Product’s circuit designs.

19 40. NXP’s Accused Processes also perform a design rule check only for each
20 net in the IC design enclosed by the ECO window. NXP does so by employing a design
21 tool, such as at least one of the Cadence, Synopsys, and/or Siemens tools, perform the
22 incremental ECO and automatically perform a DRC for those nets to ensure that the
23 ECO did not violate any design rules when it fixed other issues.

24 41. An exemplary infringement analysis showing infringement of one or more
25 claims of the ’626 patent is set forth in Exhibit B. The declaration of Lloyd Linder, an
26 expert in the field of semiconductor device design, is attached at Exhibit C and further
27 describes NXP’s infringement of the ’626 patent.

1 42. NXP’s Accused Processes infringe and continue to infringe one or more
2 claims of the ’626 patent during the pendency of the ’626 patent.

3 43. On information and belief, NXP has and continues to infringe directly
4 pursuant to 35 U.S.C. § 271, *et. seq.*, directly either literally or under the doctrine of
5 equivalents, by using the Accused Processes in violation of one or more claims of the
6 ’626 patent. NXP has and continues to infringe directly pursuant to 35 U.S.C. § 271, *et.*
7 *seq.*, directly either literally or under the doctrine of equivalents, by making, selling,
8 or offering to sell in the United States, or importing into the United States products
9 manufactured or otherwise produced using the Accused Processes in violation of one
10 or more claims of the ’626 patent.

11 44. NXP’s infringement of the ’626 patent is exceptional and entitles Bell
12 Semic to attorneys’ fees and costs incurred in prosecuting this action under 35 U.S.C.
13 § 285.

14 45. Bell Semic has been damaged by NXP’s infringement of the ’626 patent
15 and will continue to be damaged unless NXP is enjoined by this Court. Bell Semic has
16 suffered and continues to suffer irreparable injury for which there is no adequate
17 remedy at law. The balance of hardships favors Bell Semic, and public interest is not
18 disserved by an injunction.

19 46. Bell Semic is entitled to recover from NXP all damages that Bell Semic
20 has sustained as a result of NXP’s infringement of the ’626 patent, including without
21 limitation and/or not less than a reasonable royalty

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PRAYER FOR RELIEF

WHEREFORE, Bell Semic respectfully requests that this Court enter judgment in its favor as follows and award Bell Semic the following relief:

- (a) a judgment declaring that NXP has infringed one or more claims of the '626 patent in this litigation pursuant to 35 U.S.C. § 271, *et seq.*;
- (b) an award of damages adequate to compensate Bell Semic for infringement of the '626 patent by NXP, in an amount to be proven at trial, including supplemental post-verdict damages until such time as NXP ceases its infringing conduct;
- (c) a permanent injunction, pursuant to 35 U.S.C. § 283, prohibiting NXP and its officers, directors, employees, agents, consultants, contractors, suppliers, distributors, all affiliated entities, and all others acting in privity with NXP, from committing further acts of infringement;
- (d) a judgment requiring NXP to make an accounting of damages resulting from Infineon's infringement of the '626 patent;
- (e) the costs of this action, as well as attorneys' fees as provided by 35 U.S.C. § 285;
- (f) pre-judgment and post-judgment interest at the maximum amount permitted by law;
- (g) all other relief, in law or equity, to which Bell Semic is entitled.

1 Dated: November 23, 2022

/s/ Alan Block

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26 * *Pro Hac Vice* application forthcoming

27 *Attorneys for Plaintiff Bell Semiconductor,*
28 *LLC*

DEMAND FOR JURY TRIAL

Plaintiff hereby demands a jury trial for all issues so triable.

Dated: November 23, 2022

/s/ Alan Block

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